



JieXinDa Circuit Manufacturing Capability

No	Item(Description)	Manufacturing Capability(Specification)
1	Layers	1-30
2	Board Type	FR-4, CEM1, Metal core, Rogers, and other High frequency materials etc.
3	Max. PCB Board Dimension	500mm X 600mm
4	PCB Dimension Tolerance	±0.1mm
5	Finish Thickness	0.20mm - 3.2mm
6	Finish Thickness Tolerance	±10%
7	Medium Thickness	0.075mm - 5.00mm
8	Min. Conductor Width	0.1mm
9	Min. Conductor Spacing	0.1mm
10	Outer Copper Thickness	35um - 175um
11	Inner Copper Thickness	17um - 175um
12	Drilling Aperture (Mechanical drill)	0.20mm- 6.35mm
13	Hole Position Tolerance (Mechanical drill)	0.076mm
14	Into Doles (Mechanical drill)	0.15mm- 6.30mm
15	Min. Laser Drill Diameter	0.10mm
16	Max Thru Hole Aspect Ratio	1:10
17	Max Blind Via Aspect Ratio	1:10
18	Min. Blind Via Finished Hole Size	0.15MM
19	Min. Buried Via Finished Hole Size	0.15MM
20	Min. Pad Size For Test	0.2mm
21	Aperture Tolerance (Mechanical drill)	0.076mm
22	Thickness Aperture	10:1
23	Solder Mask Type	Photosensitive ink ,Curing ink , Inferior smooth printing ink
24	Min. Solder Mask Bridge	0.1mm
25	Min. Solder Mask Spacing	0.1mm
26	Impedance Tolerance	±10%
27	Surface Treatment	HAL, ENIG, Immersion Silver/TIN,OSP etc.
28	Countersink Hole	Min.depth(D)6mil;The Depth of tolerance ±6mil